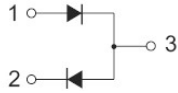
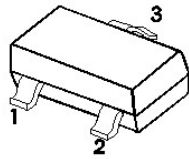


SOT-323



MARKING: KJG

特征 Features

- 开关速度小于 4nS; Fast Switching Device (TRR <4nS)
- 最大功率耗散 200mW; Power Dissipation of 200mW
- 高稳定性和可靠性。High Stability and High Reliability
- 反向漏电流小。Low reverse leakage

机械数据 Mechanical Data

- 封装: SOT-323 封装 SOT-323 Small Outline Plastic Package
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

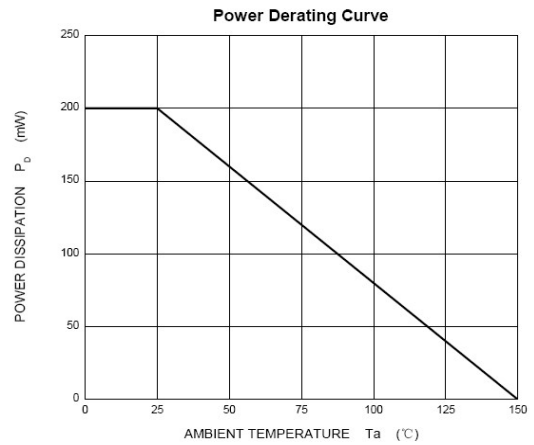
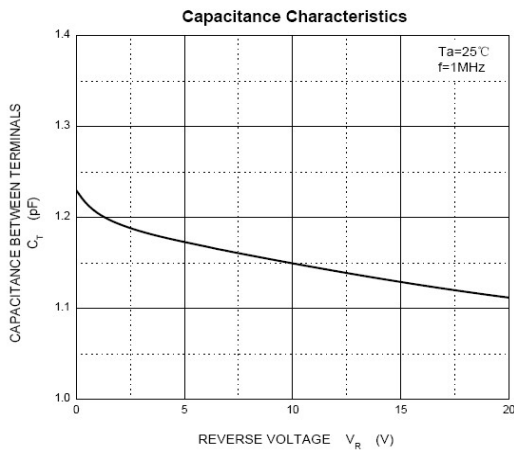
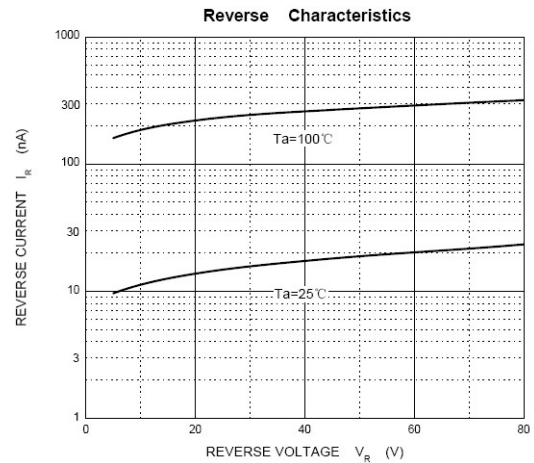
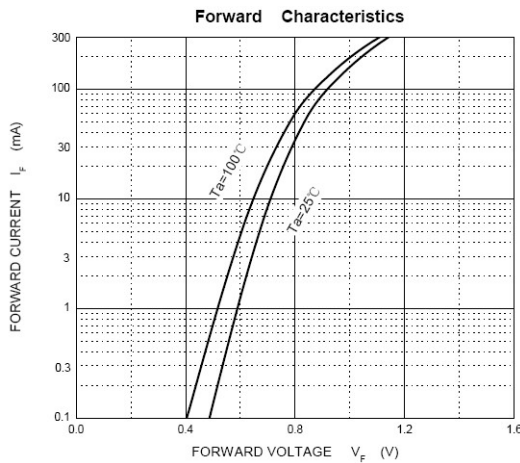
参数 Parameters	符号 Symbol	数值 Value	单位 Unit
反向电压 Reverse Voltage	V _R	90	V
峰值(不重复)电压 Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
功率消耗 Power Dissipation	P _d	200	mW
工作结温 Operating junction temperature	T _j	150	°C
存储温度 Storage temperature range	T _s	-55-+150	°C
平均整流电流 Average Rectified Current	I _O	150	mA
正向(不重复)电流 Non-repetitive Peak Forward Current	I _{FM}	300	mA
正向(不重复)浪涌电流 Peak Forward Surge Current @tp=1ms; TA=25°C	I _{FSM}	2.0	A
典型热阻 Typical thermal resistance	R _{θJA}	625	°C/W

Valid provided that electrodes are kept at ambient temperature.

电特性 **Electrical Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified.)

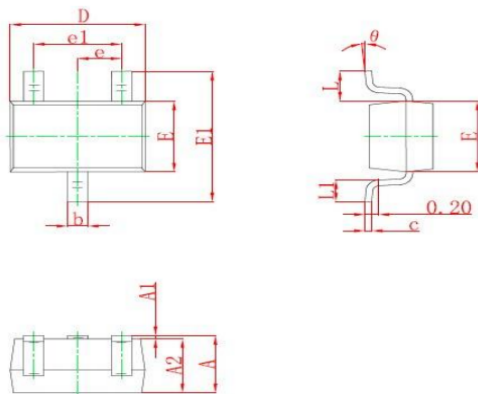
符号 Symbols	参数 Parameter	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
VRB	反向击穿电压 Reverse Voltage	I _B =100uA	90	---	V
IR	反向漏电流 Reverse Leakage Current	V _R =25V V _R =75V	---	25 2.5	nA uA
VF	正向电压 Forward Voltage	I _F =1mA	---	0.715	V
		I _F =10mA	---	0.855	
		I _F =50mA	---	1.00	
		I _F =150mA	---	1.25	
TRR	反向恢复时间 Reverse Recovery Time	I _F = I _R =10mA, R _L =100Ω I _{RR} =0.1xI _R	---	4	nS
CT	结电容 Capacitance	V _R =0V, f=1MHZ	---	2.0	pF

Typical Characteristics



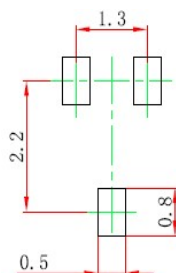
SOT-323 PACKAGE OUTLINE

Plastic surface mounted package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

焊盘设计参考 Precautions: PCB Design (Recommended land dimensions for SOT-323 diode. Electrode patterns for PCBs)



Note:
 1. Controlling dimension; in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

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